



Features:

- Isolated mounting base 3000V~
- Pressure contact technology with increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{RRM}	Type & Outline
2100V	2000V	MDx160-20-216F3
2300V	2200V	MDx160-22-216F3
2600V	2500V	MDx160-25-216F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _c =100°C	150			160	A
I _{F(RMS)}	RMS forward current		150			251	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			12	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =0.6V _{RRM}	150			4.6	kA
I ² t	I ² t for fusing coordination					105	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.84	V
r _F	Forward slope resistance					1.31	mΩ
V _{FM}	Peak forward voltage	I _{FM} =480A	25			1.66	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.23	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.08	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(max)		3000			V
F _m	Terminal connection torque(M6)				6.0		N·m
	Mounting torque(M6)				6.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				320		g
Outline	216F3						

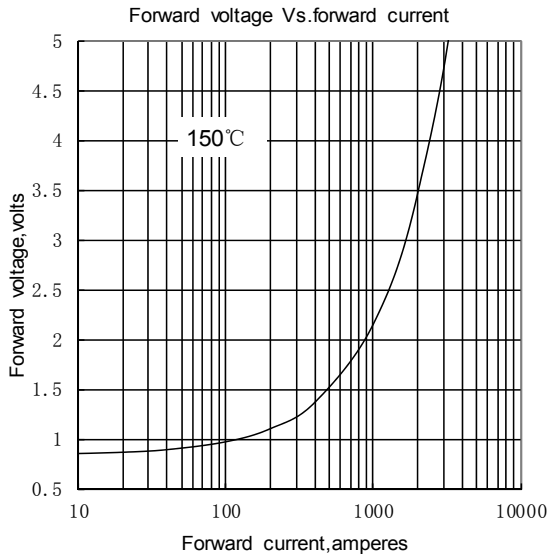


Fig.1

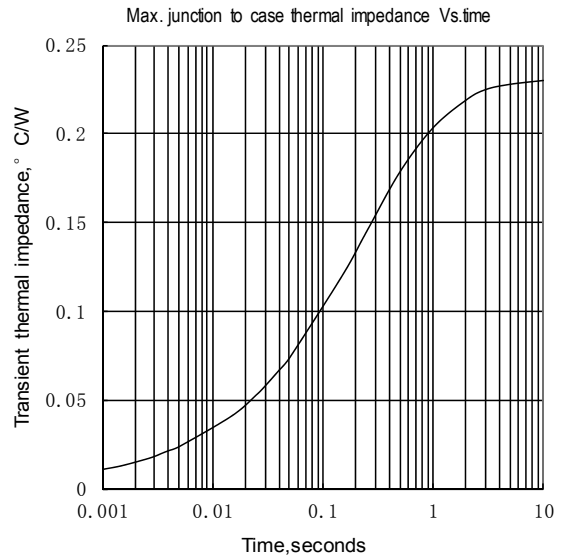


Fig.2

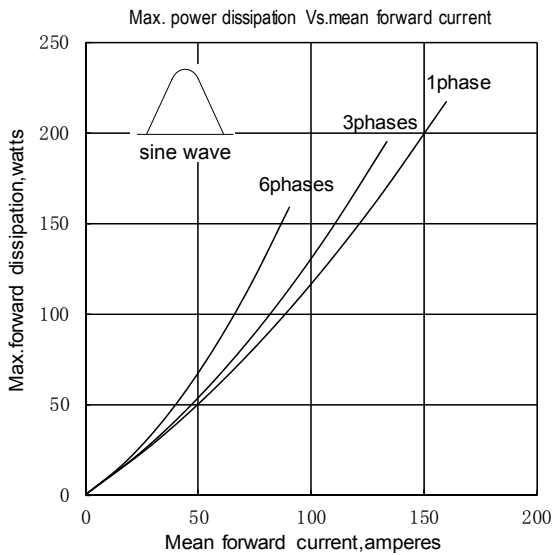


Fig.3

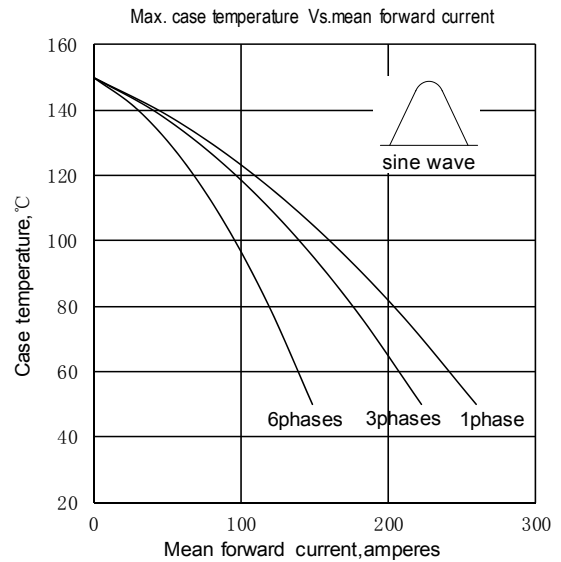


Fig.4

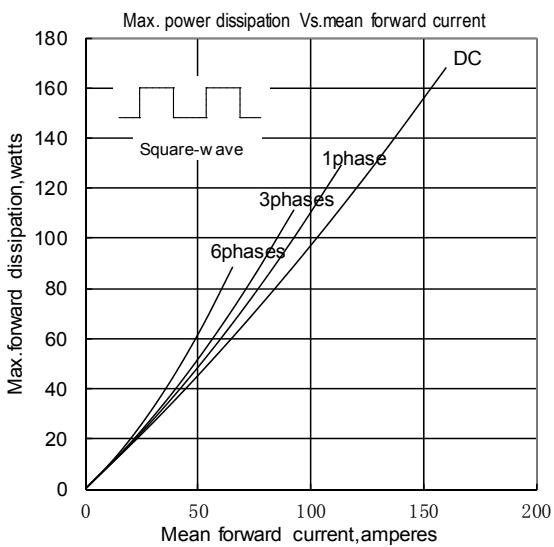


Fig.5

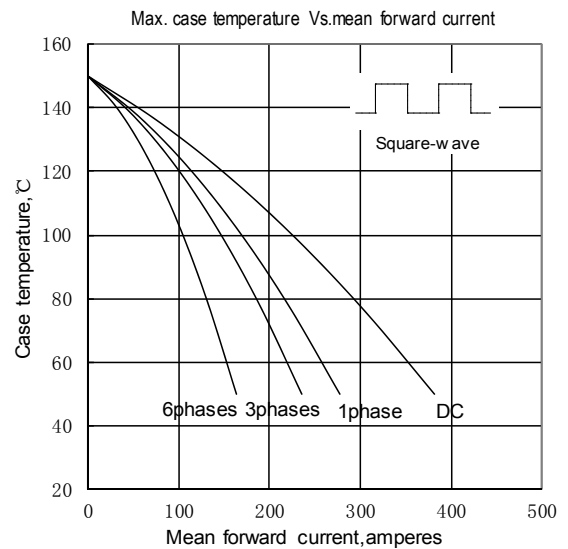


Fig.6

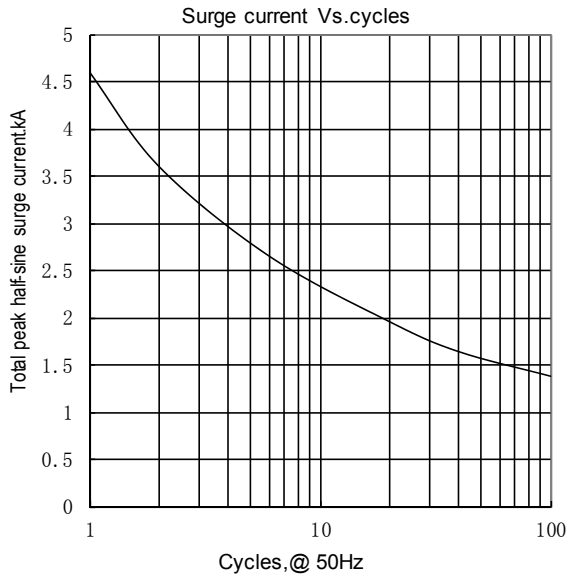


Fig.7

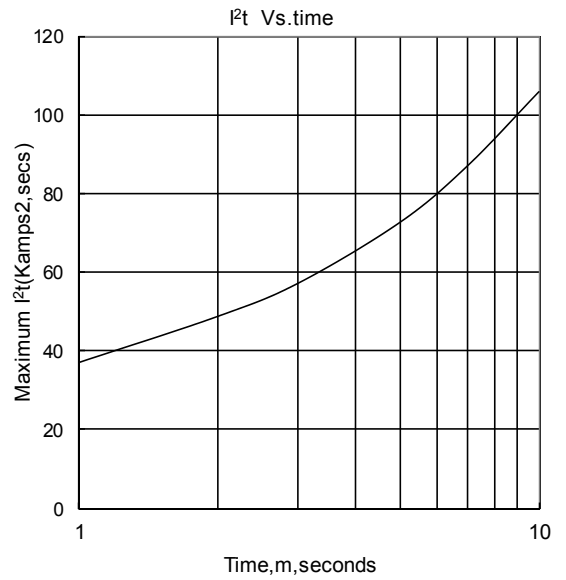
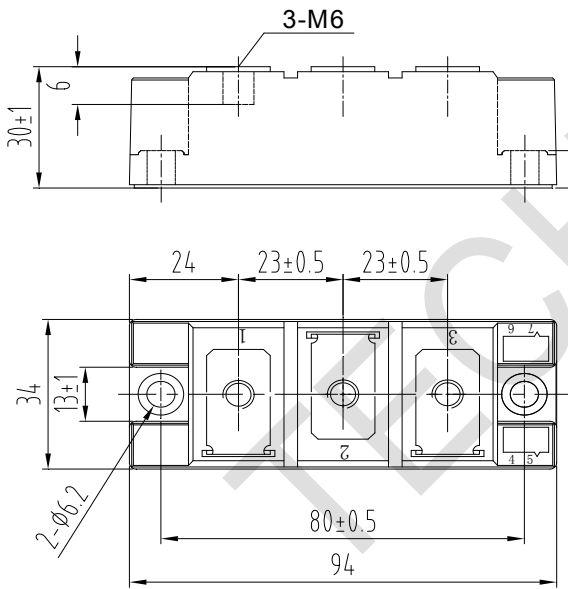


Fig.8

Outline:



- MDC
- MDA
- MDK
- MD

